



Media Advisory: Semiconductor Leaders to Debate Critical Interconnect Scaling Issues at Applied Materials Symposium

May 29, 2007

SANTA CLARA, Calif.--(BUSINESS WIRE)--May 29, 2007--Applied Materials, Inc. will host a special panel discussion featuring five experts from leading semiconductor companies to debate strategies for scaling interconnects to sub-45nm device nodes. Titled "The RC Equation: Is There an 'Easy' Answer," this important event will take place on Monday, June 4, in conjunction with the prestigious International Interconnect Technology Conference (IITC) in Burlingame, CA.

Scaling to sub-45nm interconnects will present the industry with some of its biggest and most compelling manufacturing challenges. Will the next low k material be air? How many metal layers will be needed and how will they be patterned? How will the roadmaps for memory and logic devices diverge? The panel's answers to these and other RC issues are certain to bring new insights into this critical topic and invite lively, highly-interactive discussion.

Panel:

- Dan Edelstein, IBM
- John Iacononi, AMD
- Chris Patti, SanDisk
- Gurtej Sandhu, Micron
- Farhad Moghadam, Applied Materials

Where: Hyatt Regency Hotel, 1333 Bayshore Highway,
Burlingame, CA

When: Monday, June 4, 2007
5:00pm -- Registration and reception
6:00pm -- Panel discussion and Q&A

To Register: http://www.appliedmaterials.com/2007_IITC/

Applied Materials, Inc. (Nasdaq:AMAT) is the global leader in nanomanufacturing technology(TM) solutions for the electronics industry with a broad portfolio of innovative equipment, service and software products. At Applied Materials, we apply nanomanufacturing technology to improve the way people live. Learn more at www.appliedmaterials.com.

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